SCLS336H - MARCH 1996 - REVISED JANUARY 2000

2LE

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 Members of the Texas Instruments Widebus™ Family EBIC™ (Enhanced Performance Implemented 	SN54AHCT16373 WD PACKAGE SN74AHCT16373 DGG, DGV, OR DL PACKAGE (TOP VIEW)
 EPIC[™] (Enhanced-Performance Implanted CMOS) Process 	
 Inputs Are TTL-Voltage Compatible 	
 Distributed V_{CC} and GND Pins Minimize	1Q2 [] 3 46] 1D2
High-Speed Switching Noise	GND [] 4 45] GND
 Flow-Through Architecture Optimizes PCB	1Q3 [] 5 44 [] 1D3
Layout	1Q4 [] 6 43 [] 1D4
 Latch-Up Performance Exceeds 250 mA Per	V _{CC} [7 42] V _{CC}
JESD 17	1Q5 [8 41] 1D5
 ESD Protection Exceeds 2000 V Per	1Q6 9 40 106
MIL-STD-883, Method 3015; Exceeds 200 V	GND 10 39 GND
Using Machine Model (C = 200 pF, R = 0)	1Q7 11 38 107
 Package Options Include Plastic Shrink	1Q8 12 37 1D8
Small-Outline (DL), Thin Shrink	2Q1 13 36 2D1
Small-Outline (DGG), and Thin Very	2Q2 14 35 2D2
Small-Outline (DGC), and Thin Very	GND [15 34] GND
Small-Outline (DGV) Packages and 380-mil	2Q3 [16 33] 2D3
Fine-Pitch Ceramic Flat (WD) Package	2Q4 [17 32] 2D4
Using 25-mil Center-to-Center Spacings	V _{CC} [18 31] V _{CC}
description	2Q5 [] ₁₉ 30 [] 2D5 2Q6 [] ₂₀ 29 [] 2D6
The 'AHCT16373 devices are 16-bit transparent	GND [21 28] GND
D-type latches with 3-state outputs designed	2Q7 [22 27] 2D7
specifically for driving highly capacitive or	2Q8 [23 26] 2D8

D-type latches with 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

These devices can be used as two 8-bit latches or one 16-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

OE does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54AHCT16373 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74AHCT16373 is characterized for operation from -40° C to 85° C.



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SCLS336H - MARCH 1996 - REVISED JANUARY 2000

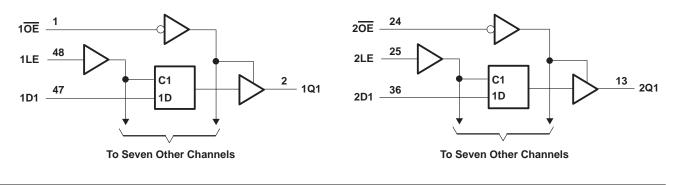
FUNCTION TABLE (each 8-bit latch)												
	INPUTS OUTPUT											
OE	LE	D	Q									
L	Н	Н	Н									
L	Н	L	L									
L	L	Q ₀										
Н	Х	Х	Z									

logic symbol[†]

1 <mark>0E</mark>	1	1EN		
1LE	48	C3		
20E	24	2EN		
2LE	25	C4		
222				
1D1	47	3D 1 ⊽	2	1Q1
1D2	46	30 1 1	3	1Q2
1D3	44		5	1Q3
1D4	43		6	1Q4
1D5	41		8	1Q5
1D6	40		9	1Q6
1D7	38		11	1Q7
1D8	37		12	1Q8
2D1	36	4D 2 ▽	13	2Q1
2D2	35		14	2Q2
2D3	33		16	2Q3
2D4	32		17	2Q4
2D5	30		19	2Q5
2D6	29		20	2Q6
2D7	27		22	2Q7
2D8	26		23	2Q8
			l	

 † This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





SCLS336H - MARCH 1996 - REVISED JANUARY 2000

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

	V nA nA nA MA VW VW VW
Storage temperature range, T _{stg} 65°C to 150°	°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 3)

		SN54AHC	T16373	SN74AHC	T16373	UNIT
		MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	N	2		V
VIL	Low-level input voltage		0.8		0.8	V
VI	Input voltage	0	5.5	0	5.5	V
Vo	Output voltage	0	Vcc	0	VCC	V
ЮН	High-level output current	20	-8		-8	mA
IOL	Low-level output current	20%	8		8	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	9	20		20	ns/V
ТА	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SCLS336H - MARCH 1996 - REVISED JANUARY 2000

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	Vaa	Τį	ς = 25°C	;	SN54AHC	T16373	SN74AHCT16373		UNIT
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
Varia	I _{OH} = -50 μA	4.5 V	4.4	4.5		4.4		4.4		V
VOH	I _{OH} = -8 mA	4.5 V	3.94			3.8		3.8		v
Ve	I _{OL} = 50 μA				0.1		0.1		0.1	V
VOL	I _{OL} = 8 mA	4.5 V			0.36		0.44		0.44	v
lj	$V_I = V_{CC} \text{ or } GND$	0 V to 5.5 V			±0.1	2	±1*		±1	μΑ
I _{OZ}	$V_{O} = V_{CC}$ or GND	5.5 V			±0.25		±2.5		±2.5	μΑ
ICC	$V_{I} = V_{CC} \text{ or GND}, \qquad I_{O} = 0$	5.5 V			4	200	40		40	μΑ
ΔI_{CC}^{\dagger}	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			1.35	PRO	1.5		1.5	mA
Ci	$V_I = V_{CC}$ or GND	5 V		2.5	10				10	pF
Co	V _O = V _{CC} or GND	5 V		4.5						pF

* On products compliant to MIL-PRF-38535, this parameter is not production tested at $V_{CC} = 0 V$.

† This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

		T _A = 2	T _A = 25°C SN54AHCT16373		73	SN74AHCT16373		UNIT
		MIN	MAX	MIN 📈 M	AX	MIN	MAX	UNIT
tw	Pulse duration, LE high	6.5		6.5		6.5		ns
t _{su}	Setup time, data before LE \downarrow	1.5		1.5		1.5		ns
th	Hold time, data after LE \downarrow	3.5		3.5		3.5		ns



SCLS336H - MARCH 1996 - REVISED JANUARY 2000

switching characteristics over recommended operating	free-air temperature range,
V_{CC} = 5 $\breve{V} \pm 0.5$ V (unless otherwise noted) (see Figure 7	1)

	FROM	то	LOAD	Τį	₄ = 25°C	;	SN54AHC	T16373	SN74AHC	T16373	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
^t PLH	D	Q	Ci = 15 pE		5.1*	8.5*	1*	9.5*	1	9.5	-
^t PHL	U	Q	C _L = 15 pF		5.1*	8.5*	1*	9.5*	1	9.5	ns
^t PLH	LE	Q	C _L = 15 pF		5*	8.5*	1*	9.5*	1	9.5	ns
^t PHL	LC	Q	CL = 15 pr		5*	8.5*	1*	9.5*	1	9.5	115
^t PZH		Q	CL = 15 pF		5*	9.5*	1*	10.5*	1	10.5	ns
^t PZL	OE		0L = 15 pr		5*	9.5*	1*	10.5*	1	10.5	115
^t PHZ	OE	Q	C _I = 15 pF		6*	10.2*	1*	11*	1	11	ns
^t PLZ	ÛE	Q	0 <u>[</u> = 15 pi		6.8*	10.2*	1*	۲ 11*	1	11	1
^t PLH	D	Q	$C_{1} = 50 \text{pF}$		5.9	9.5	J	10.5	1	10.5	ns
^t PHL	D		0L = 30 pi		5.9	9.5	7g	10.5	1	10.5	115
^t PLH	LE	Q	CL = 50 pF		6.4	9.5	x 1	10.5	1	10.5	ns
^t PHL			0L = 30 pi		5.9	9.5	1	10.5	1	10.5	115
^t PZH	OE	Q	CL = 50 pF		6	10.5	1	11.5	1	11.5	ns
^t PZL	ÛE	Q	CL = 30 pr		6	10.5	1	11.5	1	11.5	115
^t PHZ		Q	C _L = 50 pF		6.8	11.2	1	12	1	12	ns
^t PLZ	OE		0L = 30 pr		7.8	11.2	1	12	1	12	115
^t sk(o) [†]			C _L = 50 pF			1**				1	ns

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

** On products compliant to MIL-PRF-38535, this parameter does not apply.

noise characteristics, V_{CC} = 5 V, C_L = 50 pF, T_A = 25°C (see Note 4)

	PARAMETER	SN74	UNIT		
		MIN	TYP	MAX	UNIT
VOL(P)	Quiet output, maximum dynamic V _{OL}		0.32	0.8	V
VOL(V)	Quiet output, minimum dynamic V _{OL}		-0.1	-0.8	V
VOH(V)	Quiet output, minimum dynamic V _{OH}		4.7		V
V _{IH(D)}	High-level dynamic input voltage	2			V
VIL(D)	Low-level dynamic input voltage			0.8	V

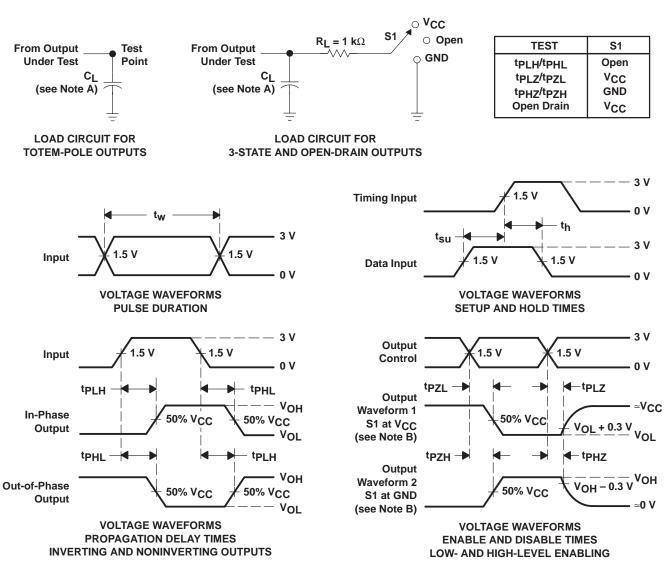
NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER		ONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load,	f = 1 MHz	22	pF



SCLS336H – MARCH 1996 – REVISED JANUARY 2000



PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f \leq 3 ns, t_f \leq 3 ns.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74AHCT16373DGGRE4	ACTIVE	TSSOP	DGG	48	2000	TBD	Call TI	Call TI
74AHCT16373DGVRE4	ACTIVE	TVSOP	DGV	48	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74AHCT16373DGGR	ACTIVE	TSSOP	DGG	48	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74AHCT16373DGVR	ACTIVE	TVSOP	DGV	48	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74AHCT16373DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AHCT16373DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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MECHANICAL DATA

PLASTIC SMALL-OUTLINE

MPDS006C - FEBRUARY 1996 - REVISED AUGUST 2000

DGV (R-PDSO-G**)

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
- D. Falls within JEDEC: 24/48 Pins MO-153

14/16/20/56 Pins – MO-194



MECHANICAL DATA

MSSO001C - JANUARY 1995 - REVISED DECEMBER 2001

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

DL (R-PDSO-G**)



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118



MECHANICAL DATA

MTSS003D - JANUARY 1995 - REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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Mailing Address:

Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

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